

semiconductor packaging news

EV Group Recognized by Bosch as a Preferred Supplier of Semiconductor Equipment – January 26, 2022

semiconductor packaging news

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January 26, 2022

[Nvidia Preparing to Abandon its Takeover of Arm](#)

Nvidia is "quietly" preparing to abandon its \$40 billion acquisition of British chip designer Arm, Bloomberg News reported. The U.S. chipmaker has told partners it's not expecting the deal to be finalized, the news agency reported, citing people familiar with the matter. SoftBank, which currently owns Arm, is ramping up preparations for Arm to go public in lieu of the Nvidia takeover ... **CNBC**



[High accuracy hybrid bonding](#)

The automated SUSS XBS300 Hybrid Bonding Platform enables hybrid and fusion bonding of 200mm and 300mm substrates with <100 nm overlay performance. **SUSS MicroTec**



[Want Better Package FA Solutions?](#)

Quickly analyze failure sites with up to 10X faster 3D X-ray microscopy and a "packaging FIB" that takes you from macro to nano in femtoseconds. Learn more in our webinar. **ZEISS Microscopy**



[VIEWPOINT 2022: William Crockett Jr., VP Bonding Wire Sales The America's, Tanaka](#)

During this time of unprecedented uncertainty, our business has remained strong with some product lines achieving record sales (ten-year tracking period). We have effectively balanced safeguarding the health of our employees and minimizing the impact on the delivery of services to our clients. ... **Tanaka**



[Optimizing cycle times in the semiconductor industry with Openair-Plasma](#)

Plasma surface treatment has many uses in semiconductor manufacturing. This process can be used for surface treatment in wire bonding and die bonding, thermal compress ... **Technical Paper**

[TSMC reportedly planning advanced packaging plant for southern Taiwan](#)

Taiwan Semiconductor Manufacturing Co. (TSMC) is reportedly planning to build an advanced packaging facility in Chiayi or Yunlin County. The potential move comes ... **Taiwan News**

[Technical Papers](#)

- [Improving Si and SiC Wafer Dicing Yields with Thermal Laser Separation](#)
- [Critical Considerations for Electronic Component Tin Whisker Mitigation](#)
- [Why AgCoat® Prime, why now?](#)
- [The New Technology Solutions for Advanced SIP Devices](#)
- [The Effects of Long-Term Storage on Solderability of Components](#)
- [Optimizing cycle times in the semiconductor industry with Openair-Plasma](#)
- [Preparing TEM Specimens and Atom Probe Tips by Laser Machining](#)

[Laser Assisted Bonding for Flip Chip](#)

For flip chip packaging with advanced Si nodes, fine bump pitch, fine LW/LS as well as large die sizes with high aspect ratios, LAB technology is the optimal methodology. Read more. **JCET**



Today's Sponsor



[Test Your Knowledge](#)

What piece of technology did IBM develop in 1973 that they nicknamed Winchester? See answer below.

[SIP Printing of the Future](#)

Welco@AP5112 Type 7 paste enables the single-step printing process for both flip-chip & passive component attach, which significantly reduces assembly cost and solder defects. **Heraeus Advanced Packaging**



[Press Releases](#)

[EV Group Recognized by Bosch as a Preferred Supplier of Semiconductor Equipment](#)

EV Group announced that it has been named a "Preferred Supplier" in the field of semiconductor by the Global Business Services Purchasing division of Robert Bosch GmbH. EVG ...

EV Group

[Ironwood adds NAND ONFI standard 194 BGA Grypper socket](#)

Ironwood continues to design new solutions using the Grypper socket technology for the newer smaller footprint devices released in the Open NAND Flash Interface (ONFI) 5.0 ...

Ironwood Electronics

[Veeco's WaferStorm Qualified By World-Leading Semiconductor Supplier](#)

Veeco Instruments Inc. announced that a world leading semiconductor supplier has qualified Veeco's WaferStorm® Wet Processing System for advanced packaging applications ...

Veeco Instruments Inc.

BGA Component Rework Simplified

When you're confronted with tough BGA rework, who do you turn to? Discover the #1 resource used by military contractors. We have solutions for all your BGA rework and repair needs.
Circuit Technology Center



Micro Dispensing Technology White Paper

The trend toward micro-dispensing technology increases as electronic assembly's shrink & component packages decrease in size.
DL Technology



Large Capacity Plasma Treatment System - FlexTRAK-SHS

9.6-liter plasma process chamber handles larger, or more, strips increasing throughput and productivity for electronics/semiconductor packaging.
MARCH | Nordson Electronics Solutions



Industry watch: Big issues must be addressed

Well known for Industry clusters, Taiwan must think about developing a "Cluster 2.0" model, ASE COO Tien Wu has urged. How should it define the concept of "mutual ...
Digitimes

North American Semiconductor Equipment Industry Posts December 2021 Billings

North America-based semiconductor equipment manufacturers posted \$3.92 billion in billings worldwide in December 2021, according to the December Equipment Market ...
SEMI

The Real Reason Behind the Automotive Industry IC Shortage--A Step-Function Surge in Demand!

IC Insights has updated and released its comprehensive forecast and analysis of the worldwide semiconductor industry in its January Semiconductor Industry Flash Report ...
IC Insights



Submicron die bonder for

- silicon photonics
- wafer-level packaging



Quote of the Day

"An education isn't how much you have committed to memory, or even how much you know. It's being able to differentiate between what you do know and what you don't."
Anatole France

The New Technology Solutions for Advanced SiP Devices

This white paper will discuss technologies that are currently being applied to System in Package (SiP) and forecast what to expect in the future.
Amkor Technology, Inc.



Die-Module Attach for High Power Devices

High flexibility film and paste adhesives for large die and module attach. Outstanding thermal conductivity with low moisture absorption stress-free bonding.
AI Technology, Inc.



What Year Was It?

Australia Day

Captain Arthur Phillip guides a fleet of 11 British ships carrying convicts to the colony of New South Wales, effectively founding Australia.



The day was Jan 26. What year was it?

Meta Aims to Build the World's Fastest AI Supercomputer

Meta, parent company of Facebook, says it has built a research supercomputer that is among the fastest on the planet. By the middle of this year, when an expansion ...
IEEE Spectrum

House Bill Funds CHIPS Act, Stresses R&D

Efforts aimed at reviving U.S. semiconductor manufacturing and strengthening technology supply chains advanced this week with the introduction of a catch-all bill that ...
EE Times

Ohio Fabs Help Advance Intel's IDM 2.0 Strategy

Intel's plan to invest more than \$20 billion in the construction of two new chip factories in Ohio underscores the chipmaker's broader integrated device manufacturing, or IDM ...
EE Times

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Artifact-free decapsulation

Preservation of original failure sites for true root cause analysis using atmospheric Microwave Induced Plasma. Breakthrough innovation in decapsulation of IC packages. Find out more.
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Accelerating Heterogeneous Integration (HI)

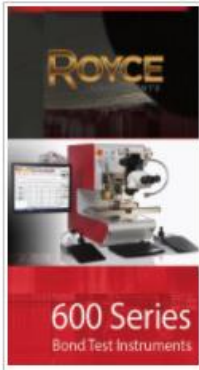
EVG provides world-class wafer-to-wafer and die-to-wafer hybrid bonding process solutions that help customers speed the deployment of HI technologies.
EV Group



Manufacturing Bits: Jan. 25

The Harvard John A. Paulson School of Engineering and Applied Sciences (SEAS) has developed a stretchable and self-powered thermometer that can be integrated ...

Semiconductor Engineering



Cartoon of the Day



"I promised you a better paycheck. It's printed with soy ink on recycled paper."
Copyright © Randy Glasbergen

Calendar

- [Jan 31, 2022: Pan Pacific Microelectronics Symposium](#)
- [Feb 3, 2022: Overview of Semiconductor Manufacturing webinar for American Attendees](#)
- [Feb 9, 2022: SEMICON Korea 2022 Hybrid](#)
- [Feb 10, 2022: Overview of Semiconductor Manufacturing/Santa Clara, Ca](#)

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Artifact-free decapsulation

Preservation of original failure sites for true root cause analysis using atmospheric Microwave Induced Plasma. Breakthrough innovation in decapsulation of IC packages. Find out more.



JIACO Instruments

How to accurately measure bumps

Accurately measure BGA bumps, vias, pin position & height, diameter & x/y dimensions. Learn how to provide accurate & repeatable measurement results at inspection speeds.



cyberTECHNOLOGIES

Test Your Knowledge Answer

What piece of technology did IBM develop in 1973 that they nicknamed Winchester?

Answer: A disk drive

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